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FLIPCHIP INTERNATIONAL AND NEC ELECTRONICS SIGN CROSS-LICENSING AGREEMENT FOR ADVANCED WAFER LEVEL PACKAGING TECHNOLOGY

PHOENIX, Arizona, KAWASAKI, Japan, April 20, 2005 — FlipChip International and NEC Electronics today announced that the two companies have entered into an extensive patent cross-licensing agreement for advanced wafer level packaging, flip chip bumping, solder bump reinforcement and wafer applied underfill technologies. As part of the agreement, FlipChip International will license its wafer level packaging patents including *Ultra* CSP™, Polymer Collar™, and Spheron™ product types to NEC Electronics. NEC Electronics will license its redistribution wafer level packaging, solder bump reinforcement and wafer applied underfill patents to FlipChip International.

Wafer level packaging, a process whereby semiconductors are packaged on the wafer prior to dicing, offers significant advantages in form factor and weight that enable real chip-scale packaging (CSP). The two companies will apply these advanced packaging technologies to devices such as discrete components, logic, ASICs, microprocessors, flash memory and other next generation devices for applications in the mobile phone, digital still camera, automotive, PDA and other emerging markets.

Commenting on the agreement, Bob Forcier, President and CEO of FlipChip International, said, “We are very pleased to commence a cross licensing agreement with NEC

Electronics for next generation flip chip and wafer level packaging, which provide substantial improvements in performance, lower costs and dramatic reductions in size compared to traditional packaging technologies. This agreement has a strong upside for both companies."

"FlipChip International is renowned for its wafer level packaging technologies, and we are confident that this cross-licensing agreement will be beneficial for both companies," said Satoshi Takabayashi, general manager, Packaging Engineering Division, NEC Electronics. "Intellectual property is essential to our business, and this agreement enables both companies to provide our respective customers with advanced wafer level packaging technologies for rapidly growing markets."

About FlipChip International

FlipChip International, LLC is a recognized technology leader in products and services for the wafer bumping and wafer scale packaging semiconductor market. FCI's licensed technology is used by the largest semiconductor assembly and test service providers worldwide. Flip Chip International, LLC is a wholly owned subsidiary of privately-held RoseStreet Labs, LLC, a supplier of products and services for wireless infrastructure in the life science, renewable energy and homeland security markets. For more information about FlipChip International, LLC, visit www.flipchip.com.

About NEC Electronics

NEC Electronics Corporation (TSE: 6723) specializes in semiconductor products encompassing advanced technology solutions for the high-end computing and broadband networking markets, system solutions for the mobile handset, PC peripherals, automotive and digital consumer markets, and platform solutions for a wide range of customer applications. NEC Electronics Corporation has 26 subsidiaries worldwide including NEC Electronics America, Inc. (www.necelam.com) and NEC Electronics (Europe) GmbH (www.ee.nec.de). For additional information about NEC Electronics worldwide, visit www.necel.com.

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